



US00D767234S

(12) **United States Design Patent** (10) **Patent No.:** **US D767,234 S**  
**Kirkland et al.** (45) **Date of Patent:** **\*\* Sep. 20, 2016**

(54) **WAFER SUPPORT RING**  
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(\*\*) Term: **14 Years**  
(21) Appl. No.: **29/519,122**  
(22) Filed: **Mar. 2, 2015**  
(51) **LOC (10) Cl.** ..... **12-05**  
(52) **U.S. Cl.**  
USPC ..... **D34/29**  
(58) **Field of Classification Search**  
USPC ..... D34/29, 28; 198/851, 853, 825, 890.1, 198/370.1, 370.04, 782, 722, 771, 866, 367, 198/790; 193/35 A, 35 C; 414/744.5, 800; D23/269  
CPC ..... H01L 21/67259; H01L 21/67742; H01L 21/67288; H02K 5/128  
See application file for complete search history.

(56) **References Cited**  
U.S. PATENT DOCUMENTS  
3,893,649 A \* 7/1975 Cornell ..... B65F 1/06 248/101  
4,867,401 A \* 9/1989 Graff ..... B65B 67/12 248/99  
4,899,967 A \* 2/1990 Johnson ..... B65B 67/12 248/97  
D457,283 S \* 5/2002 Wayt ..... D34/1  
D591,924 S \* 5/2009 Abe ..... D34/35

8,016,542 B2 \* 9/2011 Cox ..... H01L 21/67742 414/744.5  
D646,764 S \* 10/2011 Rusconi ..... D23/269  
D655,401 S \* 3/2012 Muramatsu ..... D23/269  
D667,601 S \* 9/2012 Fitzpatrick ..... D34/6  
D723,239 S \* 2/2015 Raschke ..... D34/29  
D743,513 S \* 11/2015 Yamagishi ..... D23/269  
D754,308 S \* 4/2016 Nakagawa ..... D23/269  
2004/0048474 A1 \* 3/2004 Asano ..... H01L 21/67259 438/689  
2006/0166503 A1 \* 7/2006 Sasaki ..... B24B 37/042 438/692  
2012/0263569 A1 \* 10/2012 Priddy ..... C30B 23/02 414/800  
2013/0330165 A1 \* 12/2013 Wimplinger ..... H01L 21/67288 414/800  
2014/0154038 A1 \* 6/2014 Hudgens ..... H02K 5/128 414/744.5

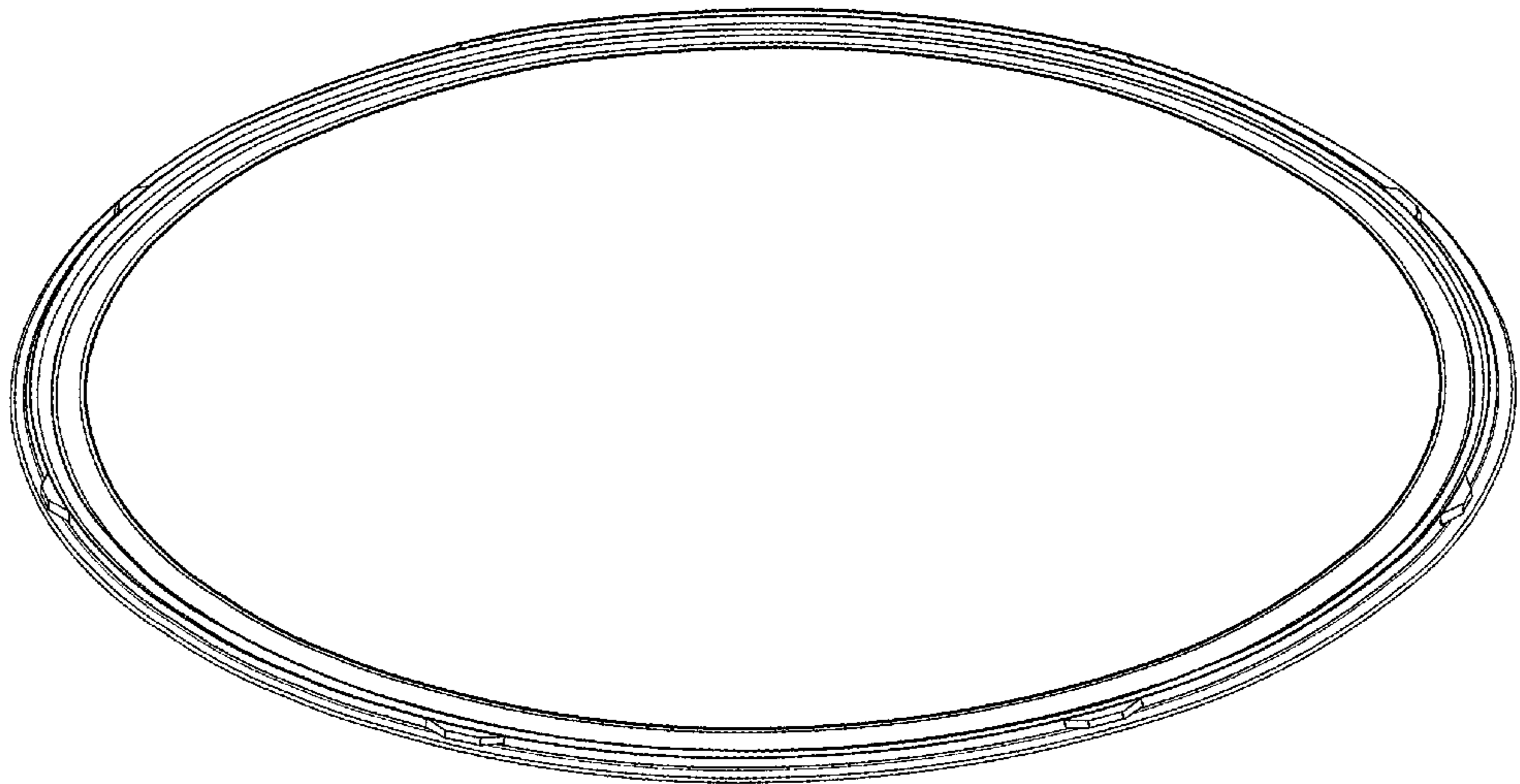
\* cited by examiner  
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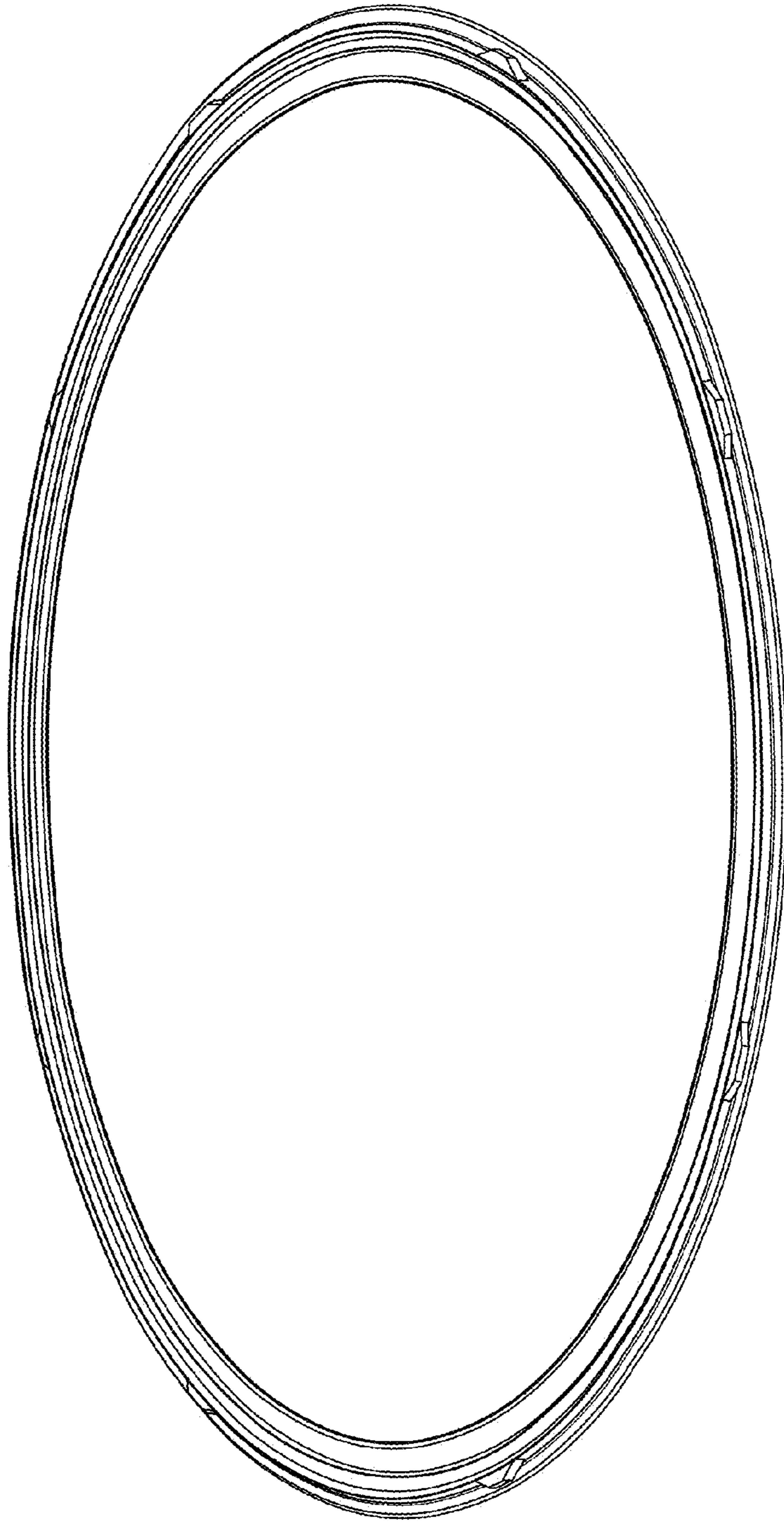
(57) **CLAIM**  
The ornamental design for a wafer support ring, as shown and described.

**DESCRIPTION**

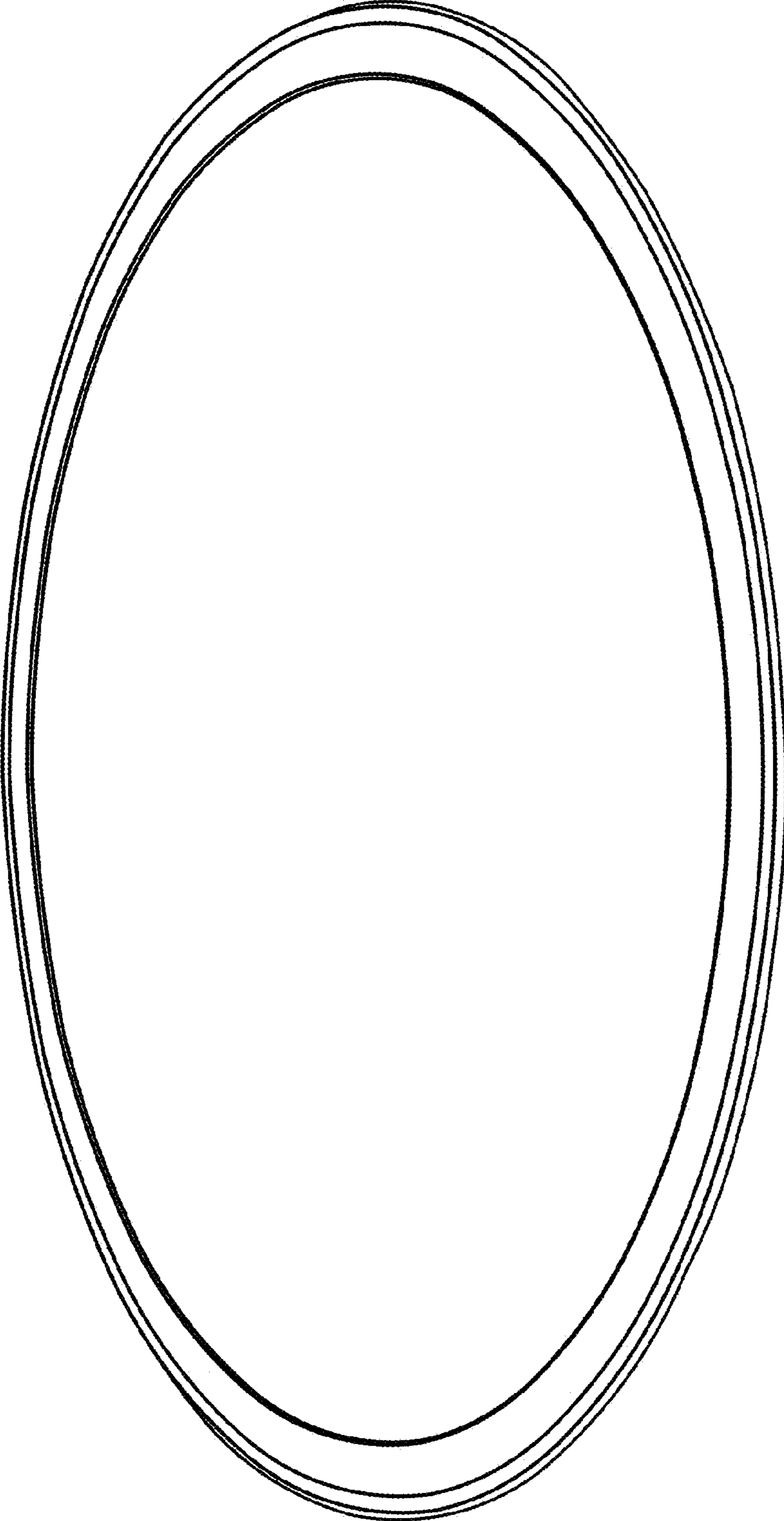
FIG. 1 is a top perspective view of a wafer support ring showing our new design;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a top plan view thereof;  
FIG. 4 is a bottom plan view thereof;  
FIG. 5 is a front elevational view, with the rear being a mirror image thereof;  
FIG. 6 is a cross sectional view taken at line 6-6 of FIG. 3; and,  
FIG. 7 is a cross sectional view taken at line 7-7 of FIG. 3.

**1 Claim, 6 Drawing Sheets**





*Fig. 1*



*Fig. 2*

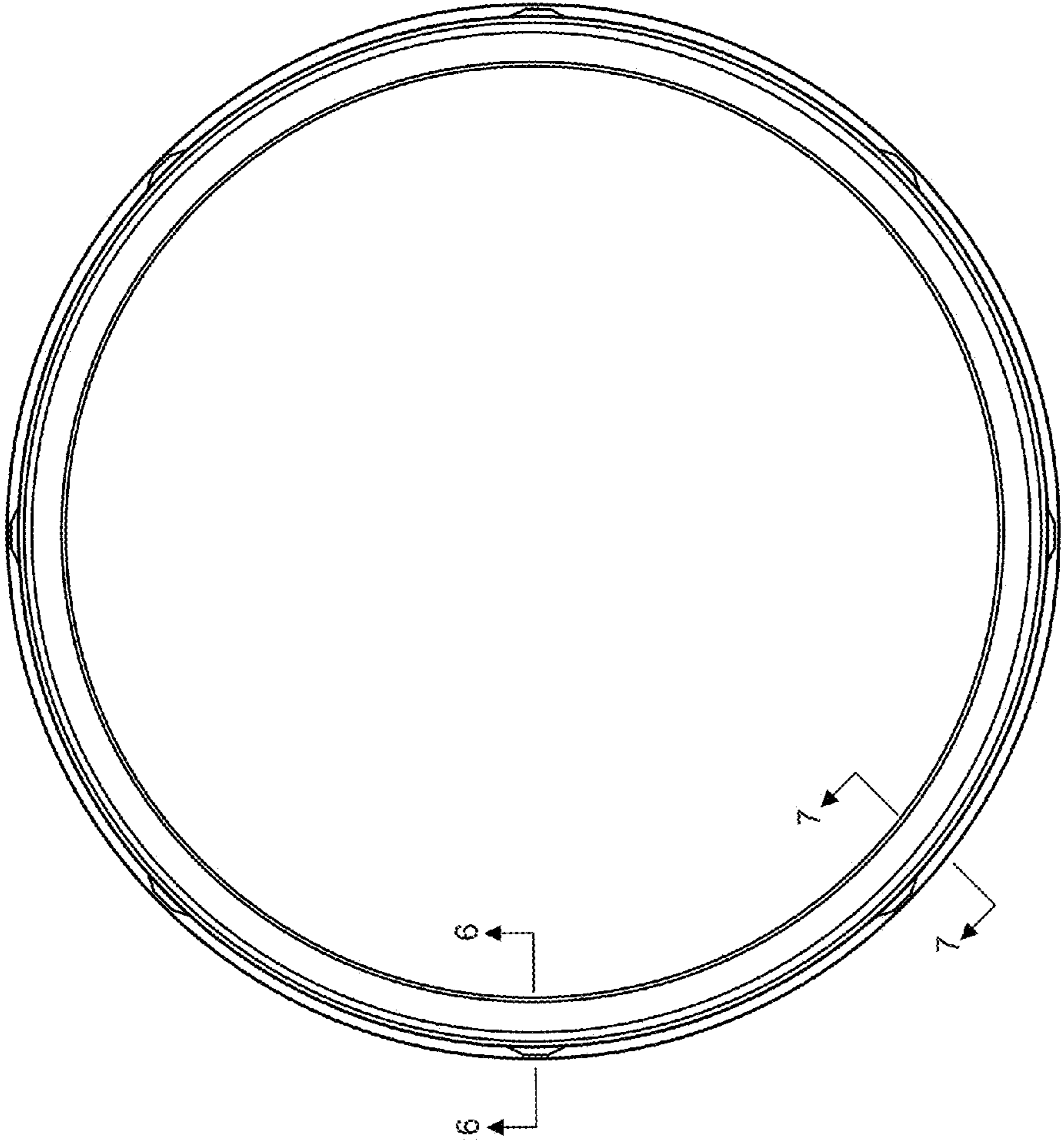
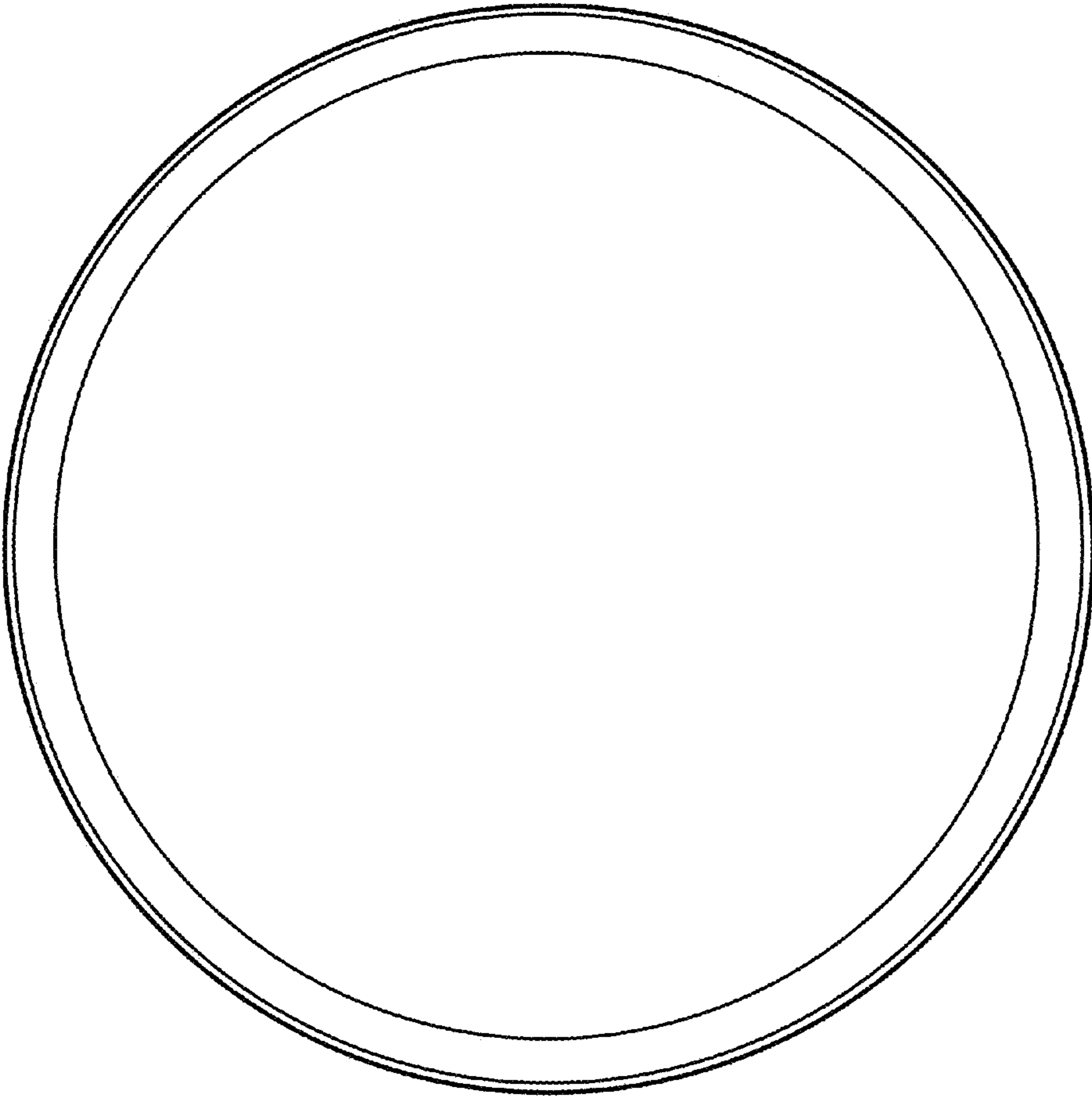


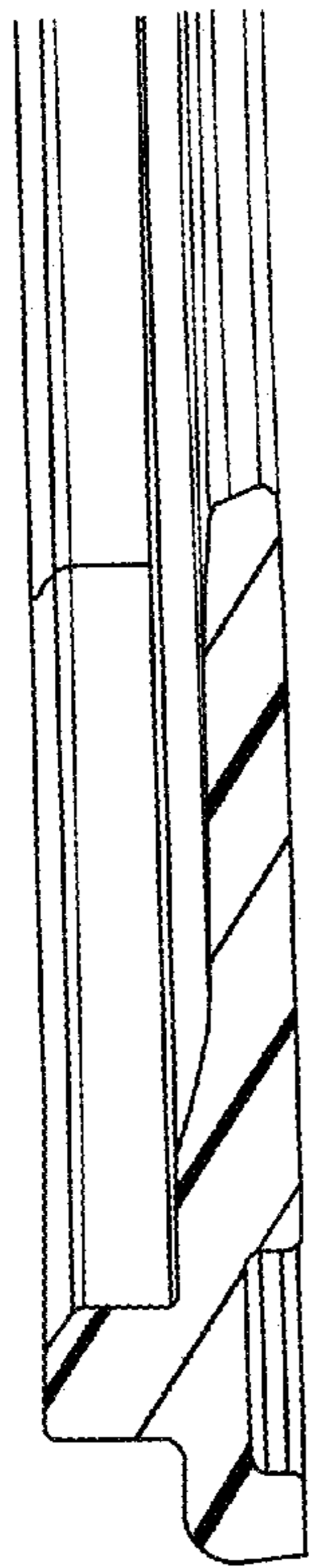
Fig. 3



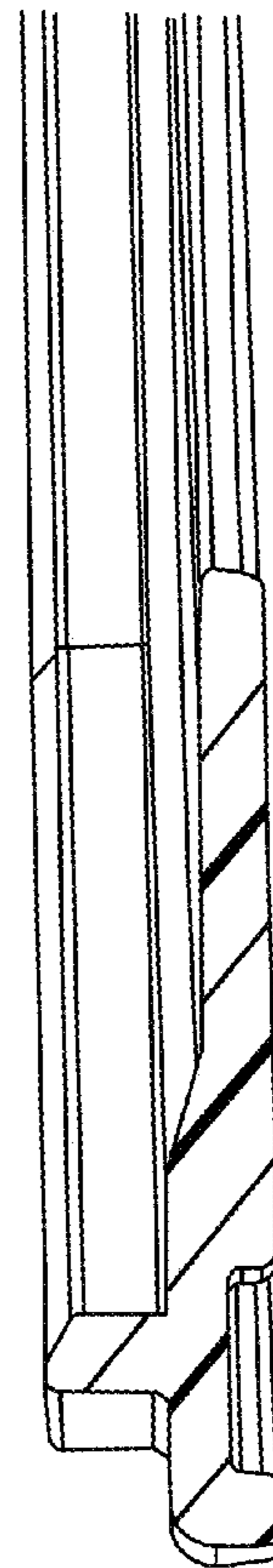
*Fig. 4*



*Fig. 5*



*Fig. 6*



*Fig. 7*